

Nitronex NPTB0004 GaN HEMT Teardown and Technology Analysis

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1. Product Identification

Manufacturer	Device ID	Date/lot code
Nitronex	NPTB0004 in PSOP2 package	06293-2

2. External Appearance and Principal Dimensions

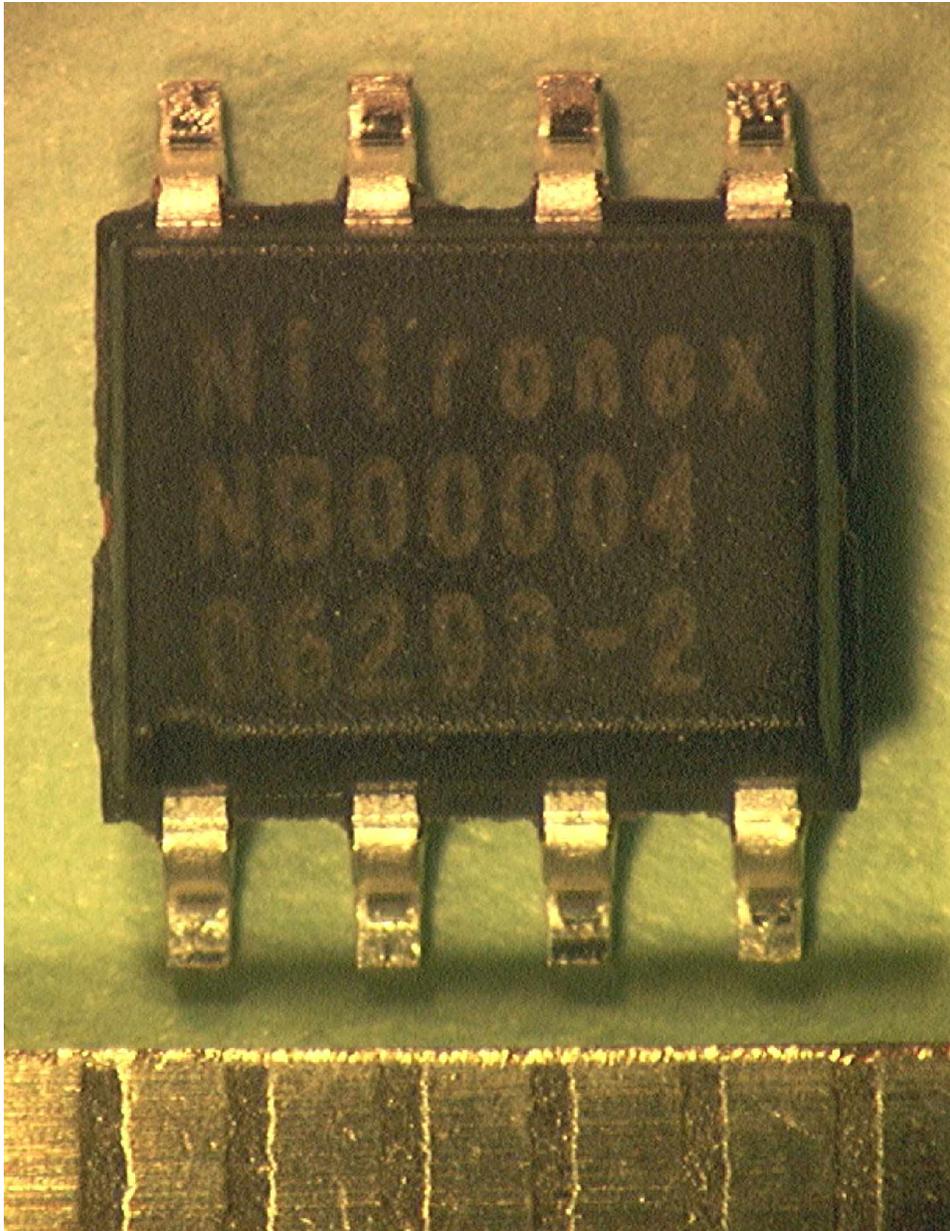


Figure 2.1: Top side of device. Ruler markings are 1mm apart

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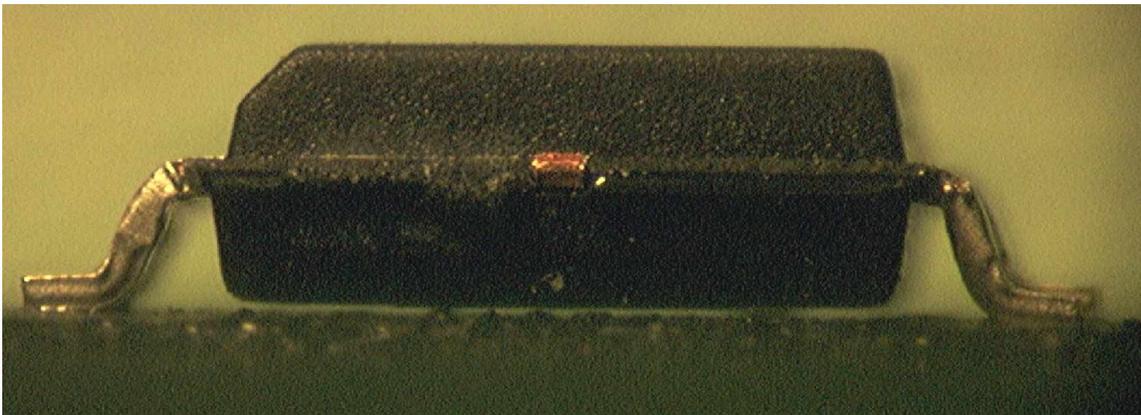
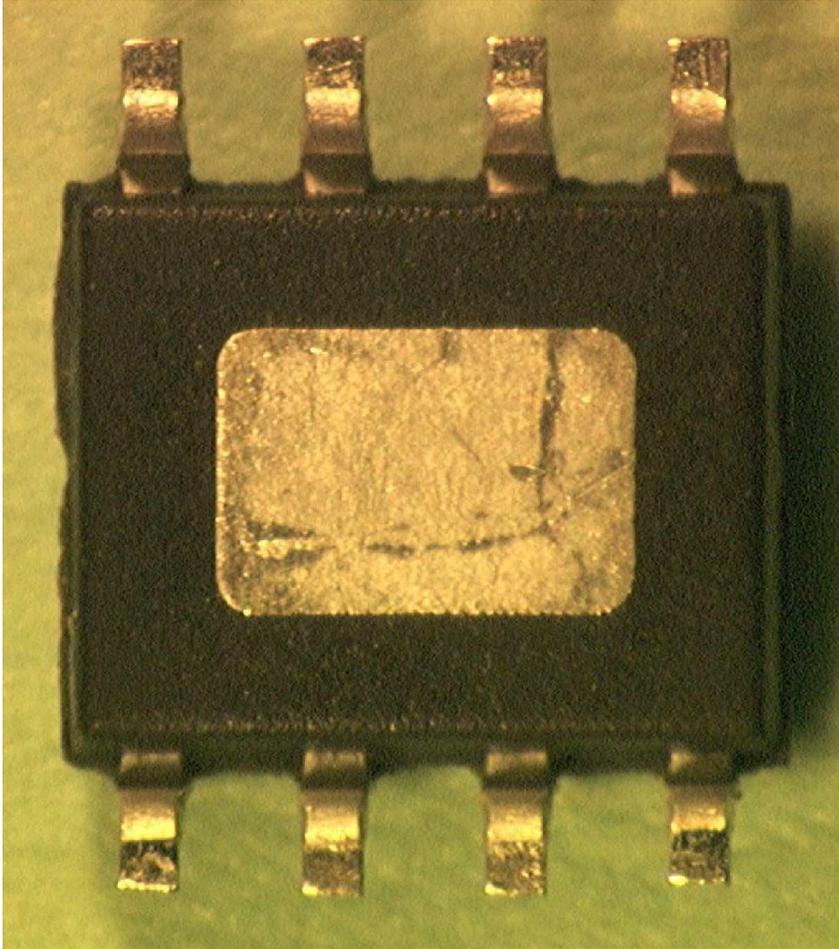


Figure 2.2: Back and end view of device.

To purchase the full report, or to request further analyses on this product, please contact sales@muanalysis.com or call 1-613-721-4664

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